



SPECIFICATION

PV03517T0150Q

- Preliminary Specification
- Final Specification

KINGTECH:

CUSTOMER:

Made By: Du xiaogang

Checked By:

Approved By:

Quality:

Date:

Note:

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Date:

Note:



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Records of Revision

| DATE | REF.PAGE PARAGRAPH DRAWING No. | REVISED No. | SUMMARY | REMARK |
|------------|--------------------------------------|-------------|----------------------------------|--------|
| 2018-12-13 | | V01 | First Issue | |
| 2019-01-08 | | V02 | Update RGB timing | |
| 2019-03-15 | | V03 | Modify the luminance and drawing | |
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Contents

| | |
|--|----|
| 1. General Specification..... | 4 |
| 2. Mechanical Drawing..... | 5 |
| 3. Block Diagram..... | 6 |
| 4. Interface Pin Function..... | 7 |
| 5. Absolute Maximum Ratings..... | 8 |
| 6. Electrical Characteristics..... | 9 |
| 7. Optical Characteristics..... | 10 |
| 8. Timing Characteristics..... | 13 |
| 9. Standard Specification for Reliability..... | 16 |
| 10. General Precautions..... | 18 |
| 11. Specification of Quality Assurance..... | 27 |
| 12. <u>packing method</u> | 28 |



1. General Specification

| Item | Contents | Unit |
|--------------------------------|-------------------|-------------|
| LCD TYPE | TFT/TRANSFLECTIVE | |
| MODULE SIZE (W*H*T) | 64*85*2.93 | MM |
| ACTIVE SIZE (W*H) | 53.64*71.52 | MM |
| PIXEL PITCH (W*H) | 0.2235*0.2235 | MM |
| NUMBER OF DOTS | 240*320 | |
| DRIVER IC | ILI9341V | |
| INTERFACE TYPE | SPI+ 18 BIT RGB | |
| TOP POLARIZER TYPE | GLARE | |
| RECOMMEND VIEWING DIRECTION | 6 | O'CLOCK |
| GRAY SCALE INVERSION DIRECTION | 12 | O'CLOCK |
| BACKLIGHT TYPE | 6-DIES WHITE LED | |
| TOUCH PANEL TYPE | WITHOUT | |



2. Mechanical Drawing

| Pin No | Symbol | Pin Description |
|--------|--------|-----------------|
| 1 | VLT | |
| 2 | OND | |
| 3 | V.L2 | |
| 4 | OND | |
| 5 | VSHD | |
| 6 | OND | |
| 7 | OND | |
| 8 | OND | |
| 9 | VSPIC | |
| 10 | OND | |
| 11 | OND | |
| 12 | OND | |
| 13 | OND | |
| 14 | OND | |
| 15 | CS | |
| 16 | OND | |
| 17 | SPD | |
| 18 | SPD | |
| 19 | OND | |
| 20 | SPD | |
| 21 | OND | |
| 22 | BS | |
| 23 | B4 | |
| 24 | B5 | |
| 25 | B6 | |
| 26 | B7 | |
| 27 | FB | |
| 28 | ENAB | |
| 29 | OND | |
| 30 | HSNC | |
| 31 | OND | |
| 32 | DC/CK | |
| 33 | OND | |
| 34 | CS | |
| 35 | C4 | |
| 36 | CS | |
| 37 | SPD | |
| 38 | SPD | |
| 39 | SPD | |
| 40 | SPD | |

| | |
|---------------------------|-----------------------------|
| Display Type | 262K COLOR TFT |
| Optimum Viewing Direction | NORMALLY WHITE TRANSPARENT |
| LCD Driver IC | 6.0" CLOCK |
| Operating Voltage | U1@3.4V |
| Operating Temperature | VSHD=2.8V |
| Storage Temperature | -20°C TO 70°C |
| Interface | SPIC 18 BIT RGB |
| Backlight | SPIC 18 BIT RGB |
| Surface Luminance | 6-LED WHITE |
| White X/Y | 130 cd/m ² (TYP) |

LED CIRCUIT DIAGRAM
19.2V@20mA

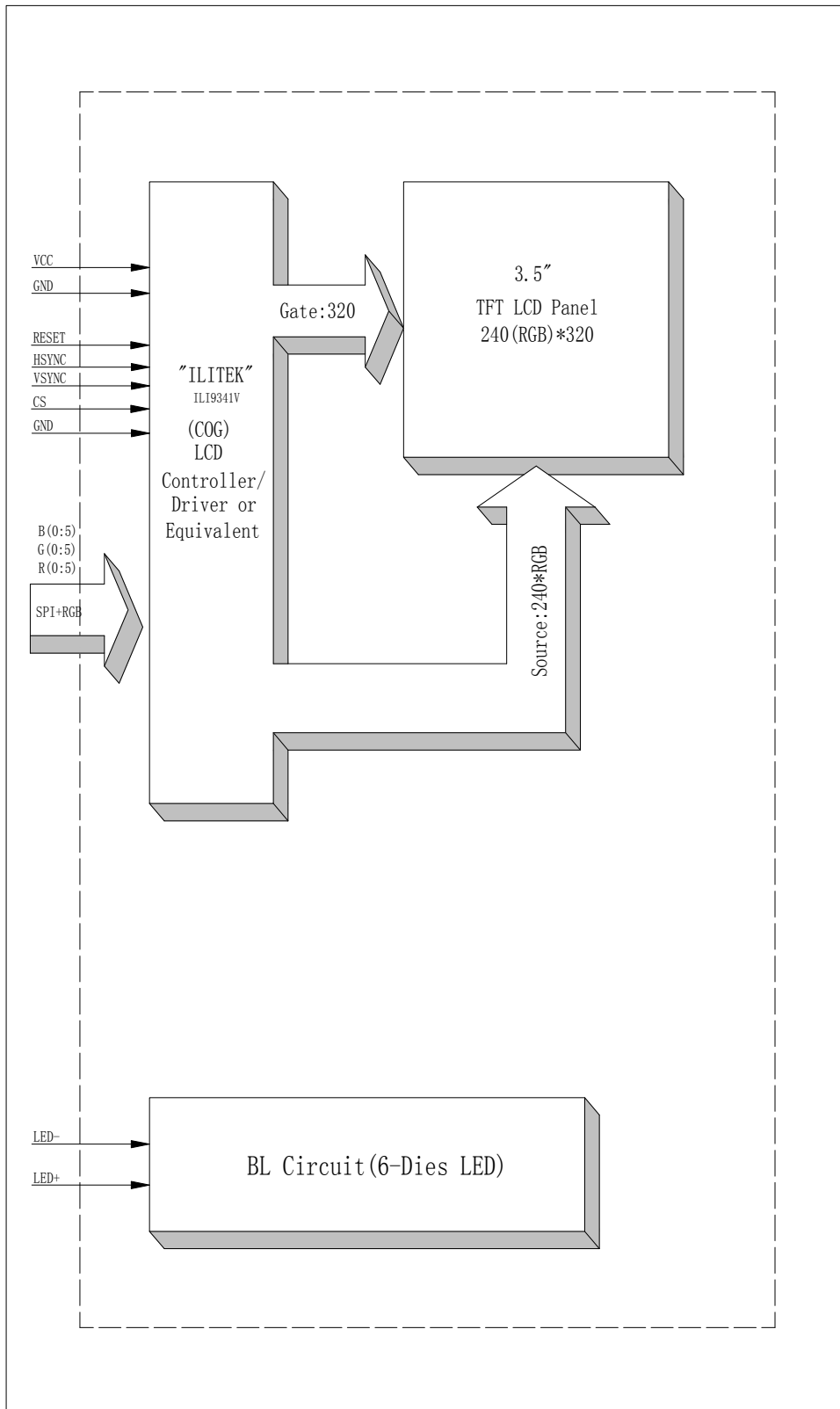
Pixel Detail
SCALE 100:1

| | | | |
|---------------------|------------|-----------|--------------|
| DRAWN | ShengNan | TITLE | MODULE SPEC. |
| ME. CHECKED | | | |
| EE. CHECKED | | | |
| APPROVED | | | |
| CUSTOMER'S APPROVAL | | | |
| DATE | 2019.03.14 | | |
| SIGN | | | |
| VER. | SYMBOl | AMENDMENT | |

Kingtech Group Co., Ltd.



3. Block Diagram





4. Interface Pin Function

| Pin No. | Symbol | Description |
|---------|--------|------------------------------------|
| 1 | VL1 | Anode of LED(High voltage) |
| 2 | GND | Power ground |
| 3 | VL2 | Cathode of LED(Low voltage) |
| 4 | GND | Power ground |
| 5 | VSHD | Power supply for digital |
| 6 | GND | Power ground |
| 7 | GND | Power ground |
| 8 | GND | Power ground |
| 9 | VSYNC | Vertical sync. in RGB mode |
| 10 | GND | Power ground |
| 11 | RESET | Reset(Low active) |
| 12 | GND | Power ground |
| 13 | GND | Power ground |
| 14 | GND | Power ground |
| 15 | CS | Chip select input(Low enable) |
| 16 | GND | Power ground |
| 17 | SD0 | Serial data output |
| 18 | SD1 | Serial data input |
| 19 | GND | Power ground |
| 20 | SCL | Serial interface clock |
| 21 | GND | Power ground |
| 22 | B5 | Blue data bus |
| 23 | B4 | Blue data bus |
| 24 | B3 | Blue data bus |
| 25 | B2 | Blue data bus |
| 26 | B1 | Blue data bus |
| 27 | B0 | Blue data bus |
| 28 | ENAB | Display enable pin from controller |
| 29 | GND | Power ground |
| 30 | HSYNC | Horizontal sync. in RGB mode |
| 31 | GND | Power ground |
| 32 | DCLK | Pixel clock signal in RGB mode |
| 33 | GND | Power ground |
| 34 | G5 | Green data bus |
| 35 | G4 | Green data bus |
| 36 | G3 | Green data bus |
| 37 | G2 | Green data bus |
| 38 | G1 | Green data bus |
| 39 | G0 | Green data bus |



| | | |
|----|-----|--------------|
| 40 | GND | No connect |
| 41 | R5 | Red data bus |
| 42 | R4 | Red data bus |
| 43 | R3 | Red data bus |
| 44 | R2 | Red data bus |
| 45 | R1 | Red data bus |
| 46 | R0 | Red data bus |
| 47 | GND | Power ground |
| 48 | GND | Power ground |
| 49 | GND | Power ground |
| 50 | GND | Power ground |

5. Absolute Maximum Ratings

| Parameter | Symbol | Min | Max | Unit |
|---------------------------|------------------|------|-----|------|
| Supply voltage for analog | VSHD | -0.3 | 4.5 | V |
| Supply voltage for logic | VSHD | -0.3 | 4.5 | V |
| Supply current (One LED) | I _{LED} | | 30 | mA |
| Operating temperature | T _{OP} | -20 | +70 | °C |
| Storage temperature | T _{ST} | -30 | +80 | °C |

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.



6. Electrical Characteristics

6.1 Input Power

| Item | Symbol | Min | Typ. | Max | Unit | Applicable terminal |
|---------------------------|-----------|----------|------|---------|---------|---------------------|
| Supply Voltage for Analog | VSHD | 3.0 | 3.3 | 3.6 | V | |
| Supply Voltage for Logic | VSHD | 3.0 | 3.3 | 3.6 | V | |
| Input Voltage | V_{IL} | GND | - | 0.3VSHD | V | |
| | V_{IH} | 0.7 VSHD | - | VSHD | | |
| Input leakage Current | I_{LKG} | -1 | | 1 | μA | |

6.2 Backlight Driving Conditions

| Item | Symbol | Value | | | Unit | Remark |
|---------------------------|--------|--------|--------|------|------|--------------|
| | | Min. | Typ. | Max. | | |
| Voltage for LED Backlight | V_F | 16.8 | 19.2 | 20.4 | V | $I_L = 20mA$ |
| Current for LED Backlight | I_L | | 20 | 30 | mA | |
| Power Consumption | P | | 0.384 | | W | |
| LED Life Time | | 30,000 | 50,000 | | Hr | Note |

Note: Brightness to be decreased to 50% of the initial value at ambient temperature $T_A = 25^\circ C$

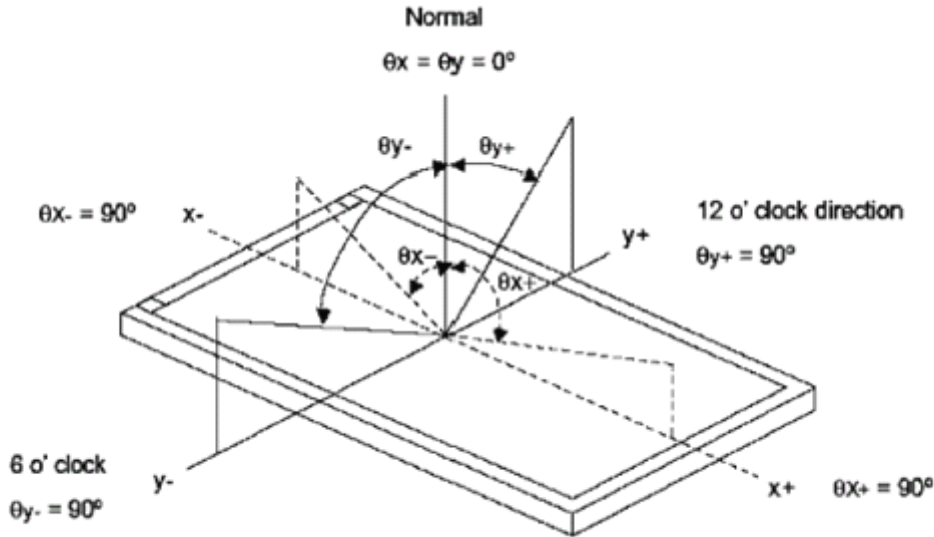


7. Optical Characteristics

| ITEM | SYMBOL | CONDITIONS | SPECIFICATIONS | | | UNIT | NOTE |
|----------------------|------------------|---------------------|----------------|-------|-------|----------------------|----------------------|
| | | | MIN | TYP. | MAX | | |
| Luminance | L | $I_L = 20\text{mA}$ | 110 | 130 | 150 | Cd/m^2 | |
| Contrast Ratio | CR | $\theta = 0^\circ$ | 100 | 150 | | | |
| Response Time | T_{ON} | 25°C | | 35 | | ms | |
| | T_{OFF} | | | | | | |
| CIE Color Coordinate | Red | X_R | 0.467 | 0.507 | 0.547 | Viewing normal angle | |
| | | Y_R | 0.287 | 0.327 | 0.367 | | |
| | Green | X_G | 0.294 | 0.334 | 0.374 | | |
| | | Y_G | 0.489 | 0.529 | 0.569 | | |
| | Blue | X_B | 0.117 | 0.157 | 0.197 | | |
| | | Y_B | 0.103 | 0.143 | 0.183 | | |
| | White | X_W | 0.284 | 0.324 | 0.364 | | |
| | | Y_W | 0.332 | 0.372 | 0.412 | | |
| Viewing Angle | Hor. | θ_{x+} | | 60 | | Degree | Gray scale inversion |
| | | θ_{x-} | | 60 | | | |
| | Ver. | θ_{y+} | | 55 | | | |
| | | θ_{y-} | | 60 | | | |
| Uniformity | Un | | 80 | | | % | |



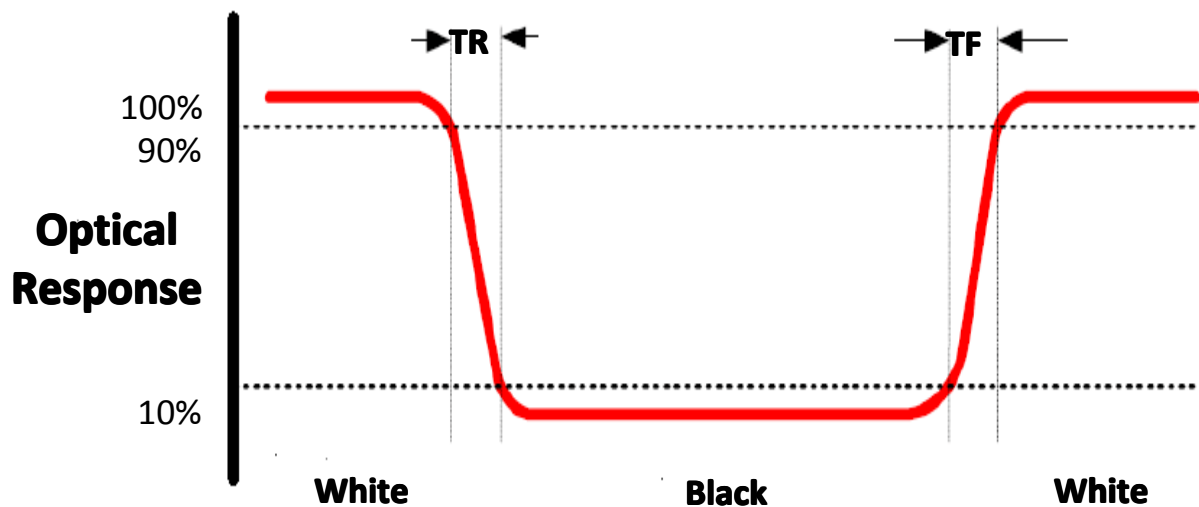
Note 1: Definition of Viewing Angle θ_x and θ_y :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{\text{Luminance of white state}}{\text{Luminance of black state}}$$

Note 3: Definition of Response Time (Tr, Tf)

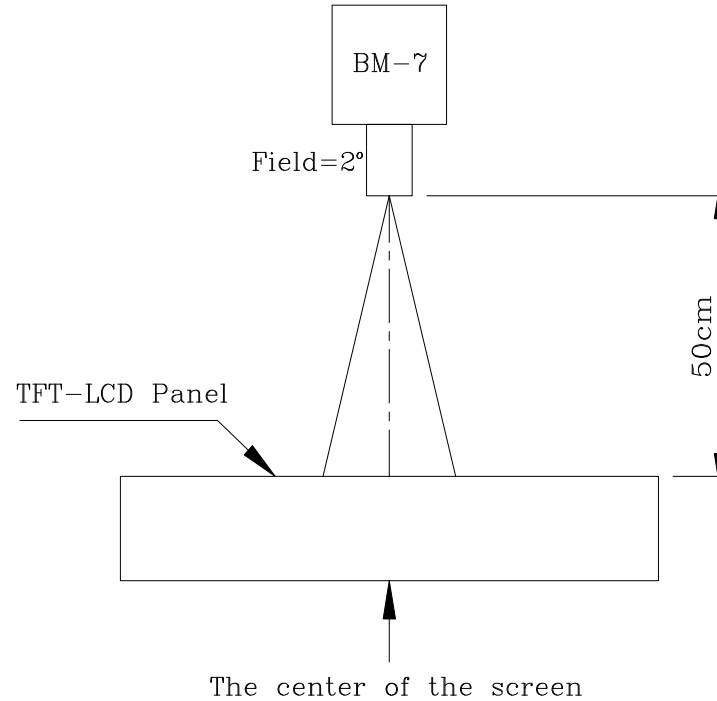




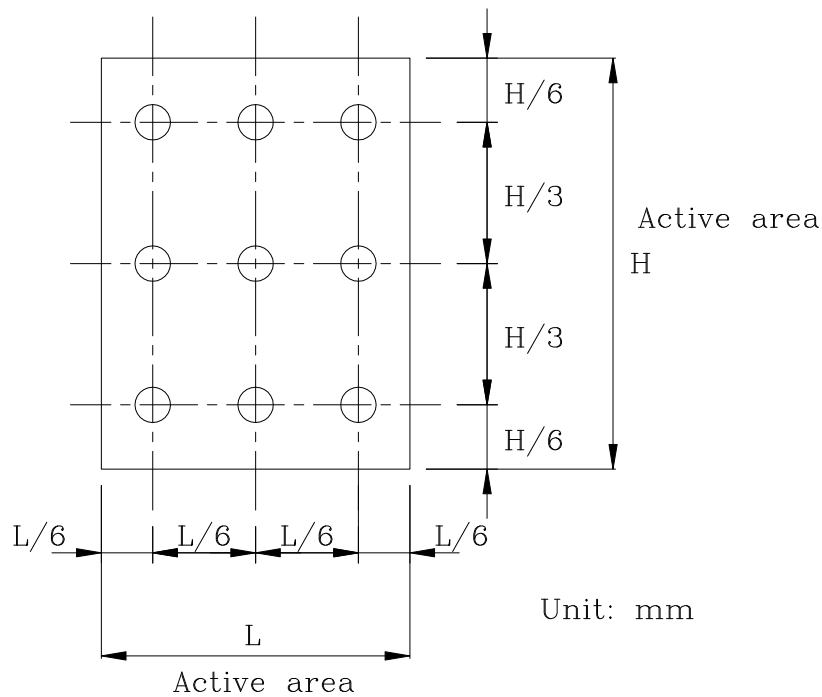
Note 4: Definition of Luminance

① The Brightness Test Equipment Setup

Field=2°(As measuring "black" image, field=2°is the best testing condition)



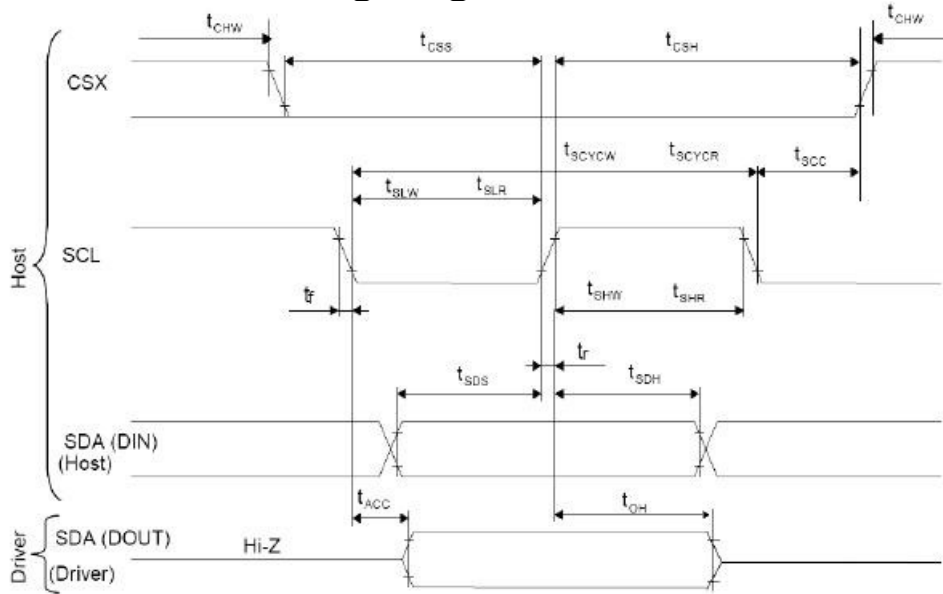
② The Brightness Test Point Setup





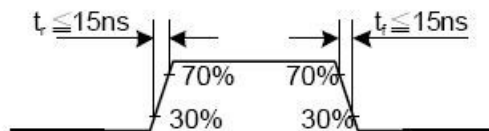
8. Timing Characteristics

8.1 3-WIRE SPI Timing Diagram



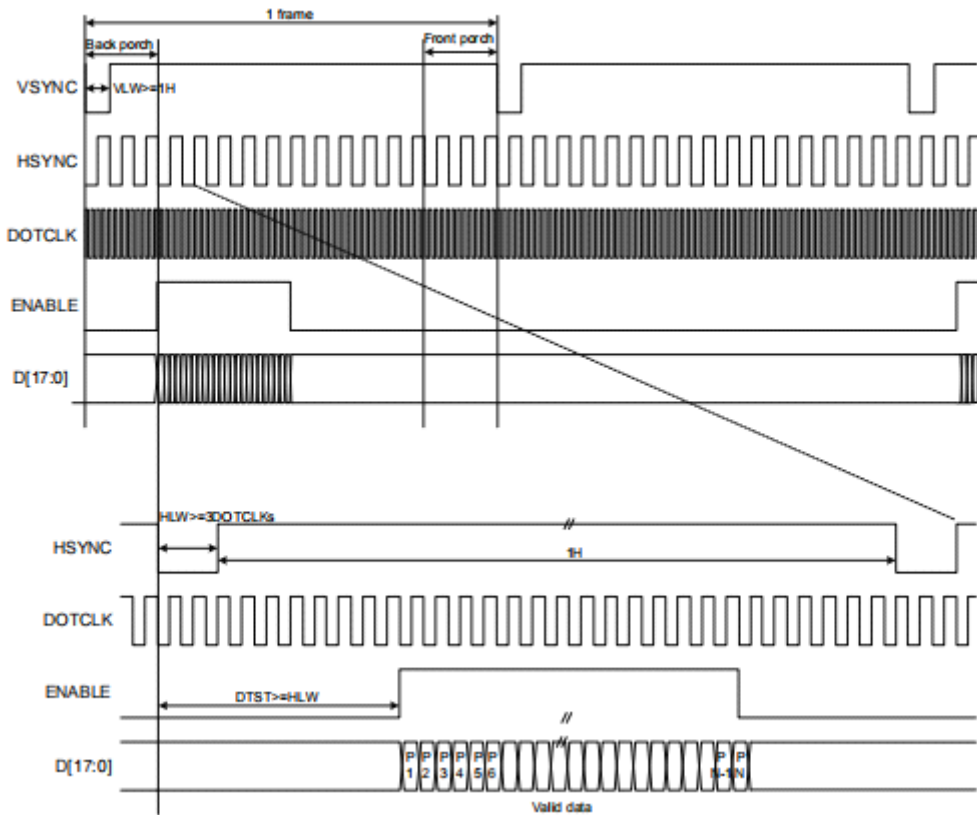
| Signal | Symbol | Parameter | min | max | Unit | Description |
|--------------------|--------|-----------------------------|-----|-----|------|-------------|
| SCL | tscycw | Serial Clock Cycle (Write) | 100 | - | ns | |
| | tshw | SCL "H" Pulse Width (Write) | 40 | - | ns | |
| | tslw | SCL "L" Pulse Width (Write) | 40 | - | ns | |
| | tscycr | Serial Clock Cycle (Read) | 150 | - | ns | |
| | tshr | SCL "H" Pulse Width (Read) | 60 | - | ns | |
| | tslr | SCL "L" Pulse Width (Read) | 60 | - | ns | |
| SDA / SDI (Input) | tsds | Data setup time (Write) | 30 | - | ns | |
| | tsdh | Data hold time (Write) | 30 | - | ns | |
| SDA / SDO (Output) | tacc | Access time (Read) | 10 | - | ns | |
| | toh | Output disable time (Read) | 10 | 50 | ns | |
| CSX | tscc | SCL-CSX | 20 | - | ns | |
| | tchwh | CSX "H" Pulse Width | 40 | - | ns | |
| | tcsw | CSX-SCL Time | 60 | - | ns | |
| | tcsh | | 65 | - | ns | |

Note: $T_a = 25\text{ }^\circ\text{C}$, $V_{DDI}=1.65\text{V to }3.3\text{V}$, $V_{CI}=2.5\text{V to }3.3\text{V}$, $AGND=VSS=0\text{V}$

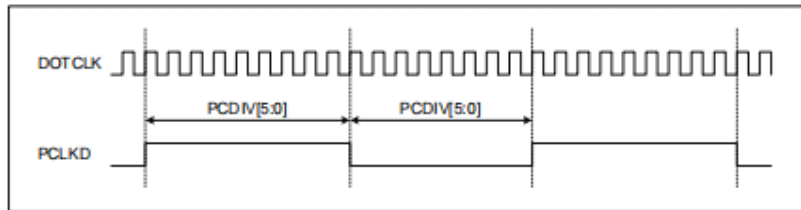




8.2 RGB Timing Diagram



VLW : VSYNC Low Width
 HLW : HSYNC Low Width
 DTST : Data Transfer Startup Time
 P : Pixel : N=240X320=76800



Note 1: The DE signal is not needed when RGB interface SYNC mode is selected.

Note 2: VSPL=0', HSPL=0', DPL=0' and EPL=0' of "Interface Mode Control (B0h)" command.



| Parameters | Symbols | Condition | Min. | Typ. | Max. | Units |
|----------------------------|---------|-----------|------|------|------|--------|
| Horizontal Synchronization | Hsync | | 2 | 10 | 16 | DOTCLK |
| Horizontal Back Porch | HBP | | 2 | 20 | 24 | DOTCLK |
| Horizontal Address | HAdr | | - | 240 | - | DOTCLK |
| Horizontal Front Porch | HFP | | 2 | 10 | 16 | DOTCLK |
| Vertical Synchronization | Vsync | | 1 | 2 | 4 | Line |
| Vertical Back Porch | VBP | | 1 | 2 | - | Line |
| Vertical Address | VAdr | | - | 320 | - | Line |
| Vertical Front Porch | VFP | | 3 | 4 | - | Line |

Typical values are setting example when used with panel resolution 240 x 320 (QVGA), clock frequency 6.35MHz and frame



9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

| No | Test Item | Condition | Remarks |
|----|--|---|---|
| 1 | High Temperature Operation | Ts = +70°C, 240 hours | IEC60068-21:2007 GB2423.2-2008 |
| 2 | Low Temperature Operation | Ta = -20°C, 240 hours | IEC60068-2-1:2007 GB/2423.1-2008 |
| 3 | High Temperature Storage | Ta = +80°C, 240 hours | IEC60068-21:2007 GB/2423.2-2008 |
| 4 | Low Temperature Storage | Ta = -30°C, 240 hours | IEC60068-21:2007 GB/2423.1-2008 |
| 5 | Storage at High Temperature and Humidity | Ta = +60°C, 90% RH max, 240 hours | IEC60068-2-78 :2001 GB/T2423.3—2006 |
| 6 | Thermal Shock (non-operation) | -30°C 30 min~+80°C 30 min, Change time:5min, 20 Cycle | Start with cold temperature, End with high temperature, IEC60068-214:1984, GB/2423.22-2002 |
| 7 | ESD | C=150pF,R=330Ω,5point/panel Air:±8Kv,5times; Contact:±4Kv,5times (Environment:15°C~35°C, 30%~60%.86Kpa~106Kpa) | IEC61000-42:2001 GB/T17626.2-2006 |
| 8 | Vibration Test | Frequency range:10~55Hz Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z (6 hours for total) | IEC60068-2-6:1982 GB/T2423.101995 |
| 9 | Mechanical Shock (Non Op) | Half Sine Wave60G 6ms, ±X,±Y,±Z 3times for each direction | IEC60068-2-27:1987 GB/T2423.5—1995 |
| 10 | Package Drop Test | Height:80cm, 1corner,3 edges,6 surfaces | IEC60068-2-32:1990 GB/T2423.8—1995 |

Note1: Ts is the temperature of panel's surface.

Note2: Ta is the ambient temperature of sample.



9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

| No. | Item | Test Model | In section Criteria |
|-----|---------------------|------------------------|--|
| 01 | Current Consumption | Refer To Specification | The current consumption should conform to the product specification. |
| 02 | Contrast | Refer To Specification | After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests. |
| 03 | Appearance | Visual inspection | Defect free. |

9.3 MTBF

| | |
|------|---|
| MTBF | Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm 5^{\circ}\text{C}$), normal humidity ($50\pm 10\%$ RH), and in area not exposed to direct sun light. |
|------|---|



10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by Kingtech.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:
Major defect: AQL = 0.65
Minor defect: AQL = 1.5
Total defects: AQL = 1.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.



10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

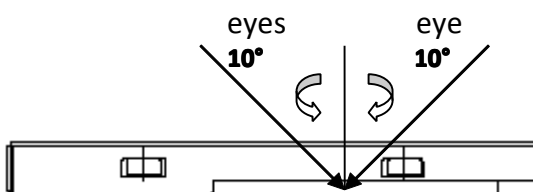
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

10.5 Standard of The Product Appearance Test

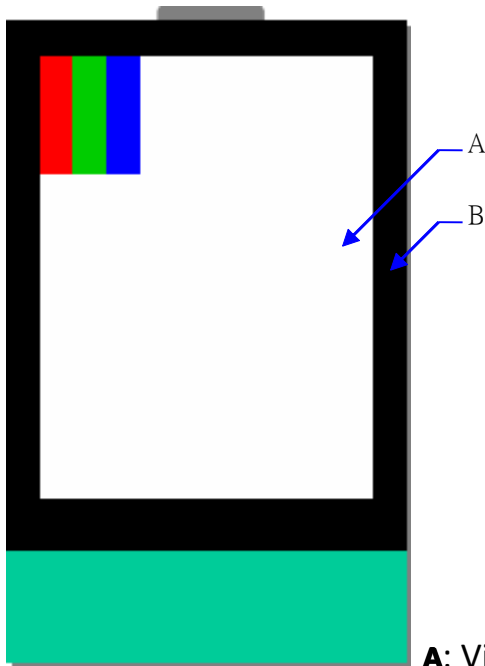
10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH





- Definition of area:



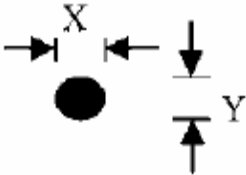
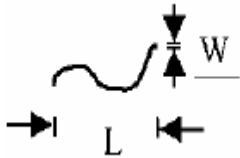
A: Viewing area **B:** Outside viewing area

10.5.2 Basic principle

- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.



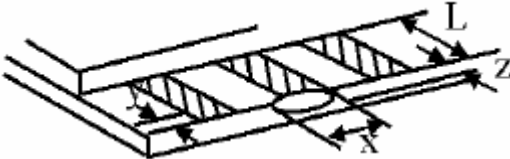
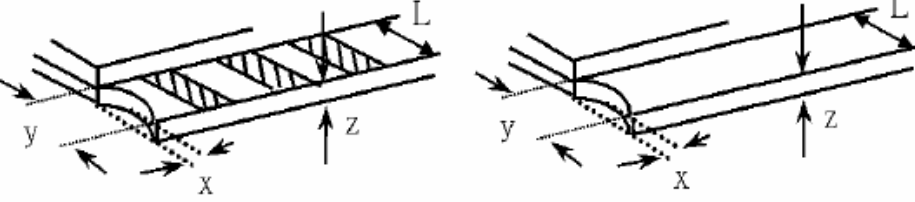
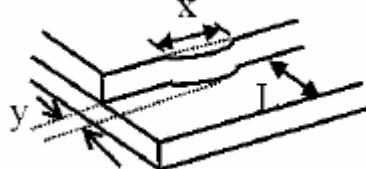
10.6 Inspection Specification

| NO. | Item | Criterion | AQL | | | | | | | | | | | | |
|--|---|--|-----------------|-----------------|------------------|-----------------|-------------------------|------------|-------------------------|-----|-------------------------|-----------|---------------|---|------------|
| 01 | Electrical Testing | 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker | 0.65 | | | | | | | | | | | | |
| 02 | Black or White spots or Bright spots or Color spots on LCD (Display only) | 2.1 White and black or color spots on display $\leq 0.25\text{mm}$, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. | 1.5 | | | | | | | | | | | | |
| 03 | LCD and Touch Panel black spots, white spots, contamination (non – display) | 3.1 Round type: As following drawing $\Phi = (X+Y) / 2$ <div style="display: flex; align-items: center; justify-content: center;">  <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>Size(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.10$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.10 < \Phi \leq 0.20$</td> <td>1</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.25$</td> <td>1</td> </tr> <tr> <td>$0.25 < \Phi \leq 0.30$</td> <td>0</td> </tr> <tr> <td>$0.30 < \Phi$</td> <td>0</td> </tr> </tbody> </table> </div> <p style="text-align: center;">* Densely spaced: No more than two spots within 3mm.</p> | Size(mm) | Acceptable Q'ty | $\Phi \leq 0.10$ | Accept no dense | $0.10 < \Phi \leq 0.20$ | 1 | $0.20 < \Phi \leq 0.25$ | 1 | $0.25 < \Phi \leq 0.30$ | 0 | $0.30 < \Phi$ | 0 | 1.5 |
| | | Size(mm) | Acceptable Q'ty | | | | | | | | | | | | |
| $\Phi \leq 0.10$ | Accept no dense | | | | | | | | | | | | | | |
| $0.10 < \Phi \leq 0.20$ | 1 | | | | | | | | | | | | | | |
| $0.20 < \Phi \leq 0.25$ | 1 | | | | | | | | | | | | | | |
| $0.25 < \Phi \leq 0.30$ | 0 | | | | | | | | | | | | | | |
| $0.30 < \Phi$ | 0 | | | | | | | | | | | | | | |
| 3.2 Line type: (As following drawing) <div style="display: flex; align-items: center; justify-content: center;">  <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>Length(mm)</th> <th>Width(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>---</td> <td>$W \leq 0.02$</td> <td>Accept no dense</td> </tr> <tr> <td>$L < 2.5$</td> <td>$W < 0.08$</td> <td>1</td> </tr> <tr> <td>---</td> <td>$0.08 \leq W$</td> <td>Rejection</td> </tr> </tbody> </table> </div> <p style="text-align: center;">* Densely spaced: No more than two lines within 3mm.</p> | Length(mm) | Width(mm) | Acceptable Q'ty | --- | $W \leq 0.02$ | Accept no dense | $L < 2.5$ | $W < 0.08$ | 1 | --- | $0.08 \leq W$ | Rejection | 1.5 | | |
| Length(mm) | Width(mm) | Acceptable Q'ty | | | | | | | | | | | | | |
| --- | $W \leq 0.02$ | Accept no dense | | | | | | | | | | | | | |
| $L < 2.5$ | $W < 0.08$ | 1 | | | | | | | | | | | | | |
| --- | $0.08 \leq W$ | Rejection | | | | | | | | | | | | | |



| NO. | Item | Criterion | AQL | | | | | | | | | |
|--|-----------------------|--|-------------------------|-----------------------|----------------|----------------|---------------|-----------------------|--------------|--------------------|-----------------|--------------|
| 04 | Polarizer bubbles | If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction | Size Φ (mm) | Acceptable Q'ty | | | | | | | | |
| | | | $\Phi \leq 0.30$ | Accept no dense | | | | | | | | |
| | | | $0.30 < \Phi \leq 0.50$ | 0 | | | | | | | | |
| | | | $0.50 < \Phi \leq 1.00$ | 0 | | | | | | | | |
| | | | $1.00 < \Phi$ | 0 | | | | | | | | |
| | | | Total Q'ty | 0 | | | | | | | | |
| 05 | Scratches | Follow NO.3 -2 Line Type. | | | | | | | | | | |
| 06 | Chipped glass | Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels: | 1.5 | | | | | | | | | |
| | | | | | | | | | | | | |
| | | <table border="1"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 2MM$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 2MM$</td> </tr> </tbody> </table> | | z: Chip thickness | y: Chip width | x: Chip length | $Z \leq 1/2t$ | Not over viewing area | $x \leq 2MM$ | $1/2t < z \leq 2t$ | Not exceed 1/3k | $x \leq 2MM$ |
| | | z: Chip thickness | | y: Chip width | x: Chip length | | | | | | | |
| | | $Z \leq 1/2t$ | | Not over viewing area | $x \leq 2MM$ | | | | | | | |
| | | $1/2t < z \leq 2t$ | | Not exceed 1/3k | $x \leq 2MM$ | | | | | | | |
| | | ⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip 6.1.2 Corner crack: | | | | | | | | | | |
| | | | | | | | | | | | | |
| | | <table border="1"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 2MM$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 2MM$</td> </tr> </tbody> </table> | | z: Chip thickness | y: Chip width | x: Chip length | $Z \leq 1/2t$ | Not over viewing area | $x \leq 2MM$ | $1/2t < z \leq 2t$ | Not exceed 1/3k | $x \leq 2MM$ |
| | | z: Chip thickness | | y: Chip width | x: Chip length | | | | | | | |
| $Z \leq 1/2t$ | Not over viewing area | $x \leq 2MM$ | | | | | | | | | | |
| $1/2t < z \leq 2t$ | Not exceed 1/3k | $x \leq 2MM$ | | | | | | | | | | |
| ⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip | | | | | | | | | | | | |

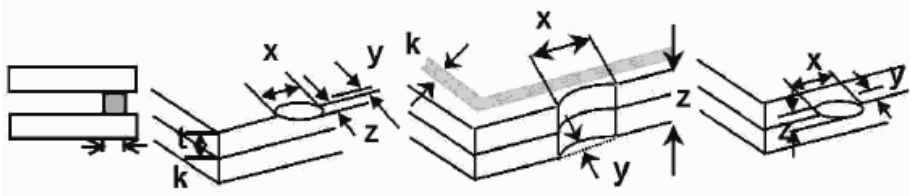
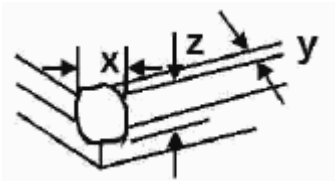


| NO. | Item | Criterion | AQL | | | | | | | | | | | | | | | | |
|-----------------------|---------------------|--|---------------|----------------|-------------------|-----------------------|---------------------|----------------|---------------|----------------|-------------------|------------|---------------------|----------------|----------|-----------|---------------|---------------------|-----|
| 07 | Glass crack | <p>Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length</p> <p>7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:</p>  <table border="1" data-bbox="558 772 1236 929"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 2\text{MM}$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>7.2.2 Non-conductive portion:</p>  <table border="1" data-bbox="558 1310 1236 1467"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 2\text{MM}$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark must not be damaged.</p> <p>7.2.3 Substrate protuberance and internal crack</p>  <table border="1" data-bbox="885 1803 1324 1937"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$x \leq 2\text{MM}$</td> </tr> </table> | y: Chip width | x: Chip length | z: Chip thickness | $y \leq 0.5\text{mm}$ | $x \leq 2\text{MM}$ | $0 < z \leq t$ | y: Chip width | x: Chip length | z: Chip thickness | $y \leq L$ | $x \leq 2\text{MM}$ | $0 < z \leq t$ | y: width | x: length | $y \leq 1/3L$ | $x \leq 2\text{MM}$ | 1.5 |
| y: Chip width | x: Chip length | z: Chip thickness | | | | | | | | | | | | | | | | | |
| $y \leq 0.5\text{mm}$ | $x \leq 2\text{MM}$ | $0 < z \leq t$ | | | | | | | | | | | | | | | | | |
| y: Chip width | x: Chip length | z: Chip thickness | | | | | | | | | | | | | | | | | |
| $y \leq L$ | $x \leq 2\text{MM}$ | $0 < z \leq t$ | | | | | | | | | | | | | | | | | |
| y: width | x: length | | | | | | | | | | | | | | | | | | |
| $y \leq 1/3L$ | $x \leq 2\text{MM}$ | | | | | | | | | | | | | | | | | | |



| NO. | Item | Criterion | AQL |
|-----|--------------------|--|--|
| 08 | Cracked glass | No crack is allowed. | 1.5 |
| 09 | Backlight elements | 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. | 1.5 1.5 0.65 |
| 10 | Bezel | No scratches with W>0.1 and Length>2.5mm. | 1.5 |
| 11 | PCB、COB | 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. | 1.5 1.5 1.5 1.5 0.65 0.65 |
| 12 | FPC | FPC damage per IPC guidelines.(IPC-A-610) Nicks or damage along the edges of the flexible printed cir-cuitry and cutouts,providing the penetration does not exceed 50% of the distance from the edge to the nearest conductor to 2.5mm[0.1in], Whichever is less. | 1.5 |
| 13 | Soldering | 13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC. 13.3 Soldering per IPC guidelines.(IPC-A-610) | 1.5 0.65 |



| NO. | Item | Criterion | AQL | | | | | | | | | | | | |
|-------------------|--|--|-------------------|---------------|----------------|------------|--|--------------|-------------------|---------------|----------------|------------|--|--------------|-----|
| 14 | Touch Panel Chipped glass | <p>Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length</p> <p>14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="448 768 1268 981"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$z \leq t$</td> <td>$\leq 1/2 k$ and not over viewing area</td> <td>$x \leq 2MM$</td> </tr> </table> <p>⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip</p> <p>14.1.2 Corner crack:</p>  <table border="1" data-bbox="448 1384 1268 1597"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$z \leq t$</td> <td>$\leq 1/2 k$ and not over viewing area</td> <td>$x \leq 2MM$</td> </tr> </table> <p>⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip</p> | z: Chip thickness | y: Chip width | x: Chip length | $z \leq t$ | $\leq 1/2 k$ and not over viewing area | $x \leq 2MM$ | z: Chip thickness | y: Chip width | x: Chip length | $z \leq t$ | $\leq 1/2 k$ and not over viewing area | $x \leq 2MM$ | 1.5 |
| z: Chip thickness | y: Chip width | x: Chip length | | | | | | | | | | | | | |
| $z \leq t$ | $\leq 1/2 k$ and not over viewing area | $x \leq 2MM$ | | | | | | | | | | | | | |
| z: Chip thickness | y: Chip width | x: Chip length | | | | | | | | | | | | | |
| $z \leq t$ | $\leq 1/2 k$ and not over viewing area | $x \leq 2MM$ | | | | | | | | | | | | | |



| NO. | Item | Criterion | AQL | | | | | | | | | | |
|--------------------|---|--|------------------------------|-----------------|-----------------|-----------------|--------------------|---|--------------------|---|-----------|---|-----|
| 15 | Touch Panel(Fish eye、dent and bubble on film) | <table border="1"> <thead> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.2$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.2 < D \leq 0.4$</td> <td>5</td> </tr> <tr> <td>$0.4 < D \leq 0.5$</td> <td>2</td> </tr> <tr> <td>$0.5 < D$</td> <td>0</td> </tr> </tbody> </table> | SIZE(mm) | Acceptable Q'ty | $\Phi \leq 0.2$ | Accept no dense | $0.2 < D \leq 0.4$ | 5 | $0.4 < D \leq 0.5$ | 2 | $0.5 < D$ | 0 | 1.5 |
| SIZE(mm) | Acceptable Q'ty | | | | | | | | | | | | |
| $\Phi \leq 0.2$ | Accept no dense | | | | | | | | | | | | |
| $0.2 < D \leq 0.4$ | 5 | | | | | | | | | | | | |
| $0.4 < D \leq 0.5$ | 2 | | | | | | | | | | | | |
| $0.5 < D$ | 0 | | | | | | | | | | | | |
| 16 | Touch Panel Newton ring | Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$) , it is acceptable. | 1.5 | | | | | | | | | | |
| 17 | Touch Panel Linearity | Less than 2.5% is acceptable. | 1.5 | | | | | | | | | | |
| 18 | LCD Ripple | Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g | 1.5 | | | | | | | | | | |
| 19 | General appearance | 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 19.5 product packaging shall be by trays sized to protect tft and fpc cable, 19.6 cable shall not be bent during transportation. 19.7top tray must be empty. | 0.65 0.65 0.65 0.65 | | | | | | | | | | |



11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of $25\pm 10^{\circ}\text{C}$, and in a relative humidity of $50\pm 10\%\text{RH}$. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than $280\pm 10^{\circ}\text{C}$ and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.



12.Packing Method

| No. | Item | Dimensions(mm) | Quantity | Remark |
|-----|--------------|---|----------|--------|
| 1 | LCM Module | 64.00*85.00*2.93 | 162PCS | |
| 2 | TRAY | 385*340*21 (include 9pcs products/one tray) | 9PCS | |
| 3 | SMALL CARTON | 392*345*115 (include 81pcs products/one carton) | 2PCS | |
| 4 | LARGE CARTON | 405*355*260 (include 162pcs products/one carton) | 1PCS | |